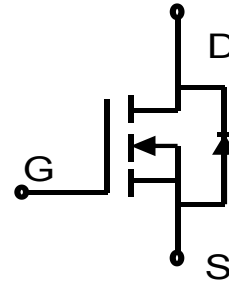




### Description

These N-Channel enhancement mode power field effect transistors are using split gate trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.



N-Channel MOSFET

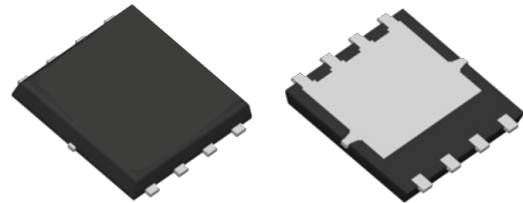
### Features

- ◆ 30V,99A,  $R_{DS(on),max} = 2.4m\Omega @ V_{GS} = 10V$
- ◆ Improved dv/dt capability
- ◆ Fast switching
- ◆ 100% EAS Guaranteed
- ◆ Green device available

### Applications

- ◆ Motor Drives
- ◆ UPS
- ◆ DC-DC Converter

### Pin Configuration



DFN5×6

### Product Summary

$V_{DSS}$	30V
$R_{DS(on),max} @ V_{GS}=10V$	2.4mΩ
$I_D$	99A

### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DSS}$	30	V
Continuous drain current ( $T_C = 25^\circ C$ ) ( $T_C = 100^\circ C$ )	$I_D$	99	A
		72	A
Pulsed drain current <sup>1)</sup>	$I_{DM}$	297	A
Gate-Source voltage	$V_{GSS}$	±20	V
Avalanche energy <sup>2)</sup>	$E_{AS}$	45	mJ
Power Dissipation	$P_D$	50	W
Storage Temperature Range	$T_{STG}$	-55 to +150	°C
Operating Junction Temperature Range	$T_J$	-55 to +150	°C

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	2.5	°C/W
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	50	°C/W

### Package Marking and Ordering Information

Device	Device Package	Marking	Units/Reel
WLQ024R03	DFN5X6	WLQ024R03	5000



### Electrical Characteristics

$T_J = 25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static characteristics</b>						
Drain-source breakdown voltage	$BV_{DSS}$	$V_{GS}=0\text{ V}, I_D=250\mu\text{A}$	30	---	---	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.2	1.7	2.5	V
Drain-source leakage current	$I_{DSS}$	$V_{DS}=30\text{ V}, V_{GS}=0\text{ V}$	---	---	1	$\mu\text{A}$
Gate leakage current, Forward	$I_{GSSF}$	$V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$	---	---	100	nA
Gate leakage current, Reverse	$I_{GSSR}$	$V_{GS}=-20\text{ V}, V_{DS}=0\text{ V}$	---	---	-100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=10\text{ V}, I_D=20\text{ A}$	---	1.9	2.4	mΩ
		$V_{GS}=4.5\text{ V}, I_D=20\text{ A}$	---	2.7	3.6	mΩ
Forward transconductance	$g_{fs}$	$V_{DS}=5\text{ V}, I_D=20\text{ A}$	---	89	---	S
<b>Dynamic characteristics</b>						
Input capacitance	$C_{iss}$	$V_{DS}=15\text{ V}, V_{GS}=0\text{ V},$ $F=1\text{ MHz}$	---	3035	---	pF
Output capacitance	$C_{oss}$		---	1590	---	
Reverse transfer capacitance	$C_{rss}$		---	209	---	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=15\text{ V}, V_{GS}=10\text{ V}, I_D=20\text{ A}$ $R_G=3.3\Omega$	---	12.3	---	ns
Rise time	$t_r$		---	6.1	---	
Turn-off delay time	$t_{d(off)}$		---	38.2	---	
Fall time	$t_f$		---	11.7	---	
Gate resistance	$R_g$	$V_{GS}=0\text{ V}, V_{DS}=0\text{ V}, F=1\text{ MHz}$	---	1.6	---	Ω
<b>Gate charge characteristics</b>						
Gate to source charge	$Q_{gs}$	$V_{DS}=15\text{ V}, I_D=20\text{ A},$ $V_{GS}=10\text{ V}$	---	12.5	---	nC
Gate to drain charge	$Q_{gd}$		---	15	---	
Gate charge total	$Q_g$		---	37	---	
<b>Drain-Source diode characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_S$		---	---	41	A
Pulsed Source Current <sup>3)</sup>	$I_{SM}$		---	---	123	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0\text{ V}, I_S=20\text{ A}, T_J=25^\circ\text{C}$	---	---	1.2	V

#### Notes:

- 1: Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2:  $V_{DD}=25\text{ V}, V_{GS}=10\text{ V}, L=0.1\text{ mH}, I_{AS}=30\text{ A}$ , Starting  $T_J=25^\circ\text{C}$ .
- 3: Pulse Test: Pulse Width  $\leq 300\ \mu\text{s}$ , Duty Cycle  $\leq 2\%$ .



### Electrical Characteristics Diagrams

Figure 1. Typ. Output Characteristics

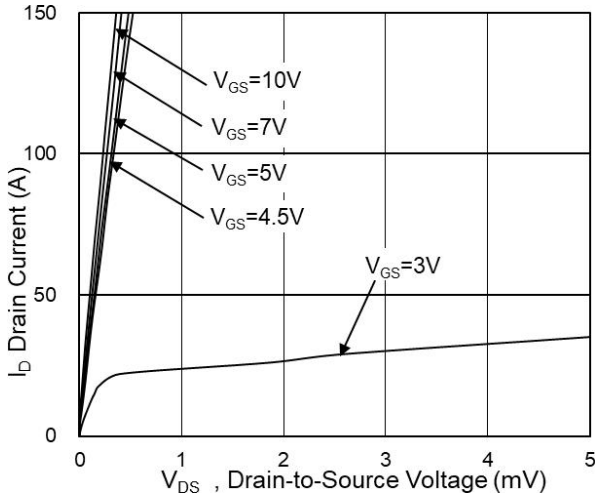


Figure 2. Transfer Characteristics

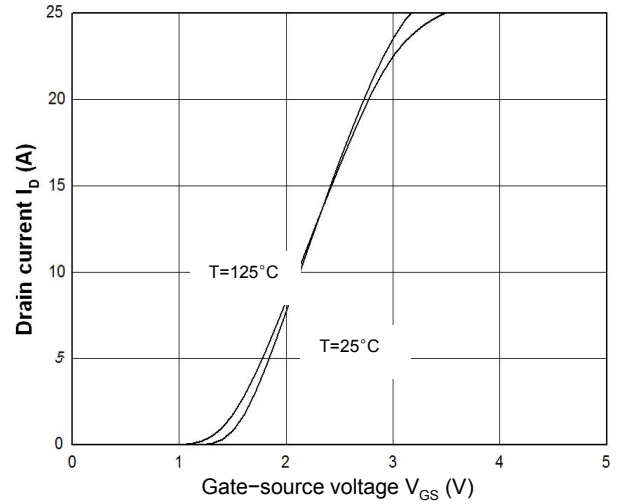


Figure 3. Capacitance Characteristics

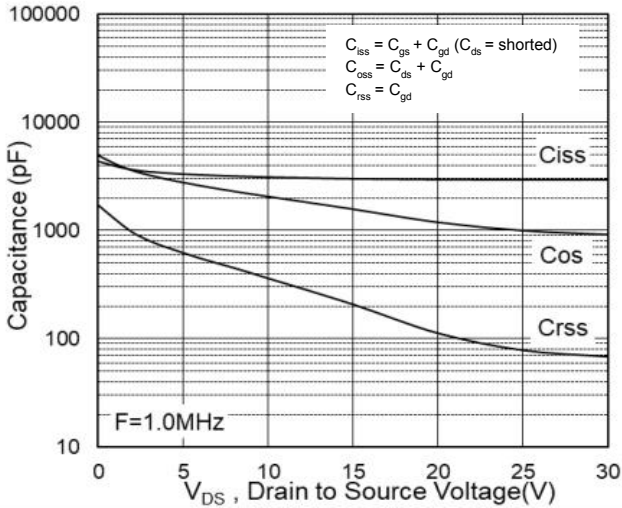


Figure 4. Gate Charge Waveform

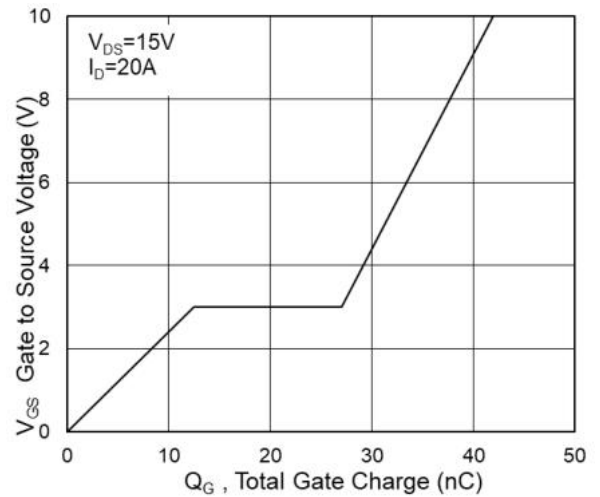


Figure 5. Body-Diode Characteristics

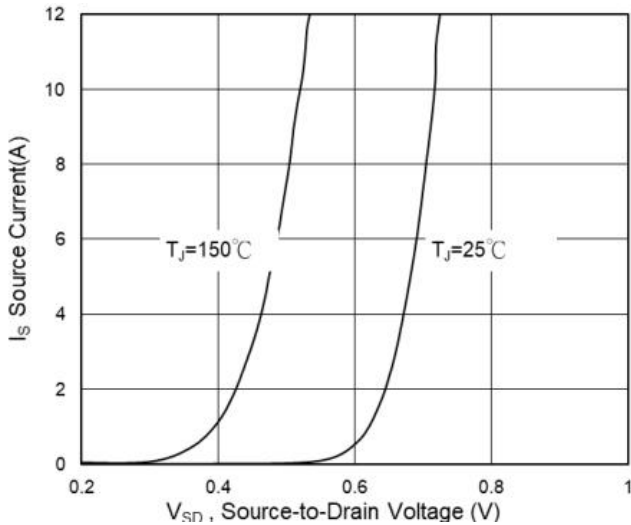


Figure 6. Rds(on)-Drain Current

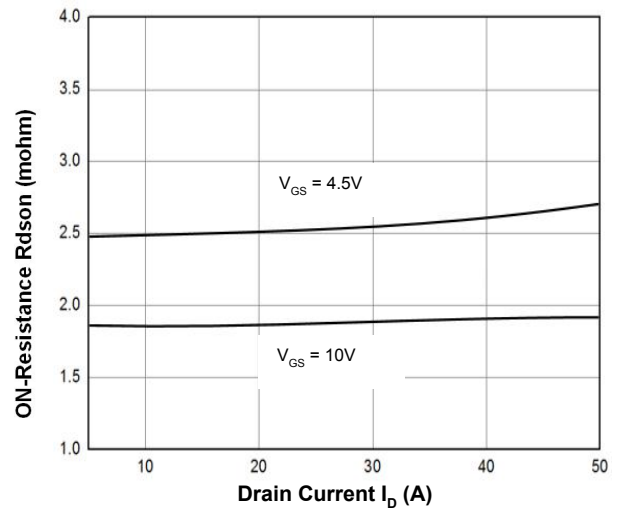




Figure 7. Rdson-Junction Temperature

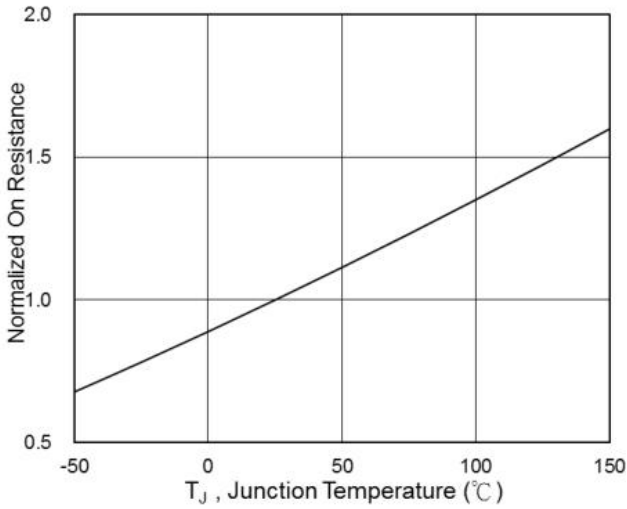


Figure 8. VGS(th)-Junction Temperature

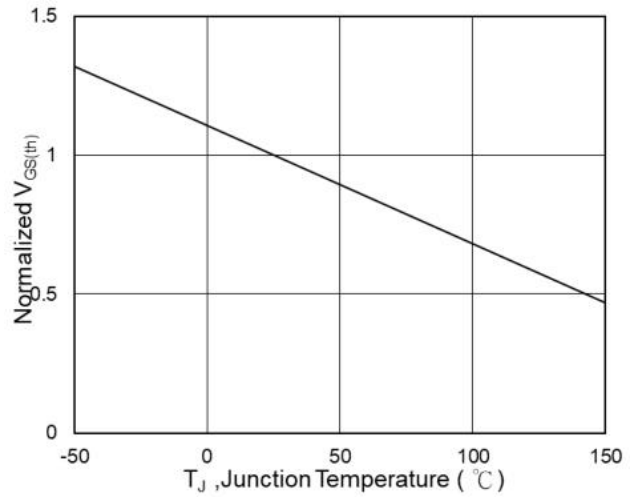


Figure 9. On-Resistance vs. Gate-to-Source voltage

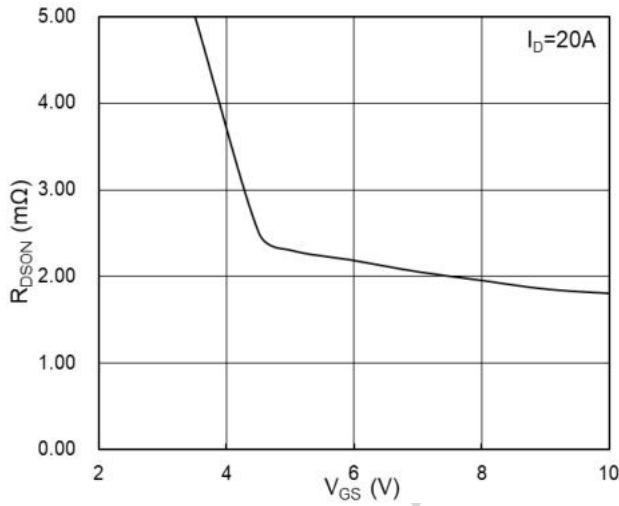


Figure 10: Safe Operating Area

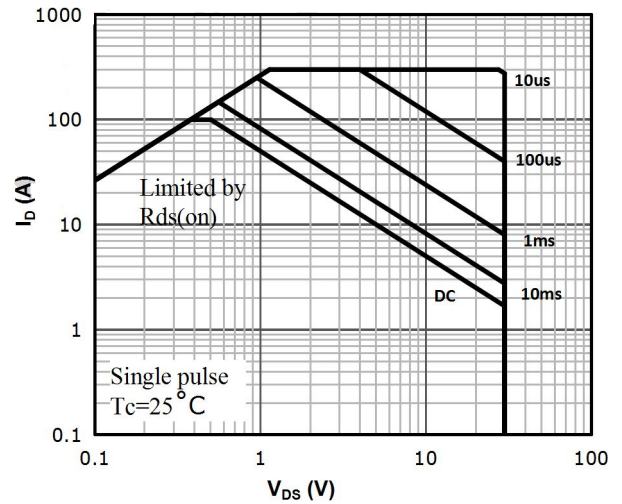
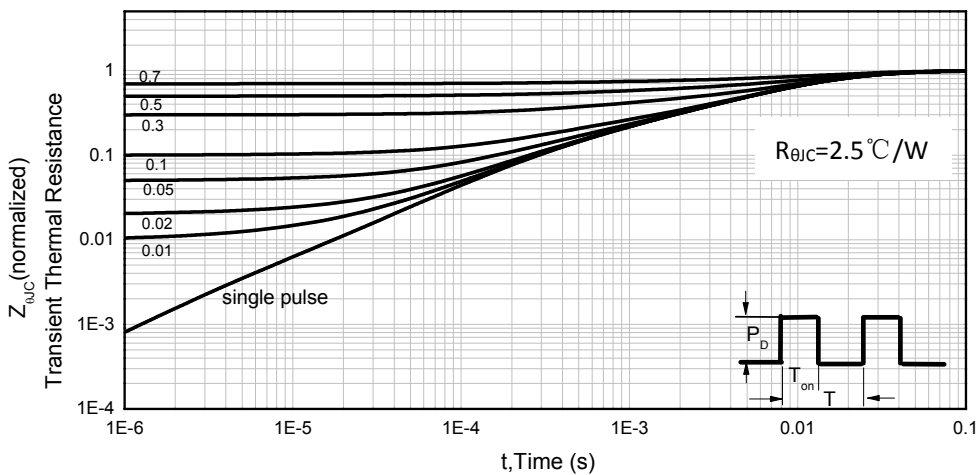


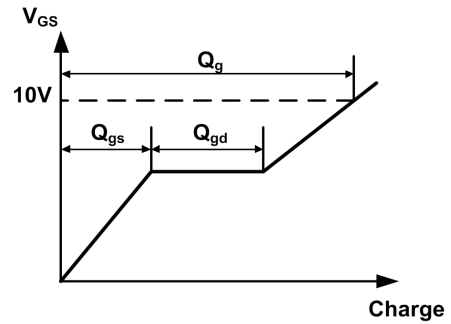
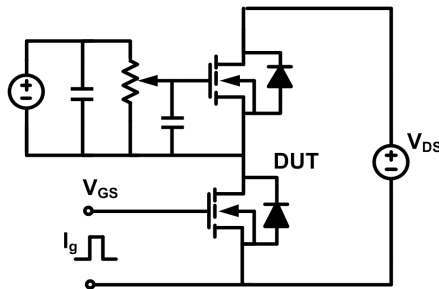
Figure 11. Normalized Maximum Transient Thermal Impedance (RthJC)



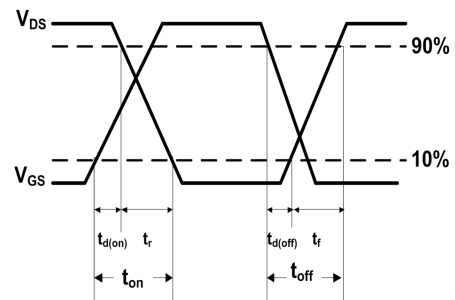
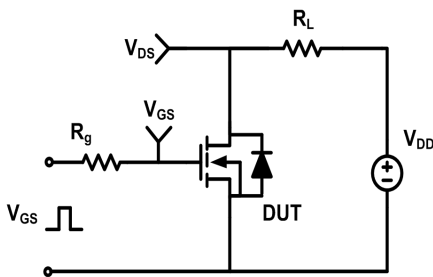


### Test Circuit & Waveforms

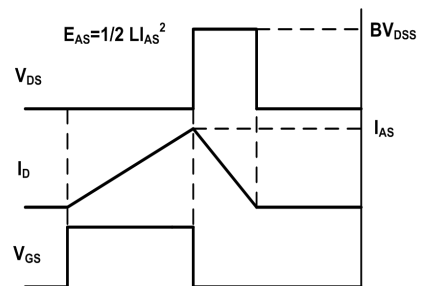
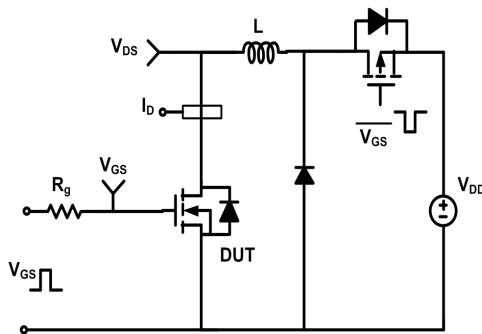
#### Gate Charge Test Circuit & Waveform



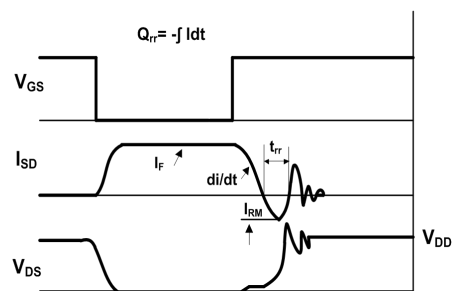
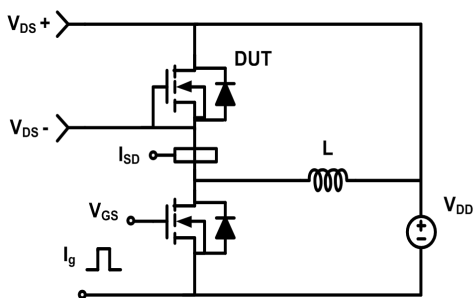
#### Resistive Switching Test Circuit & Waveform



#### Unclamped Inductive Switching (UIS) Test Circuit & Waveform

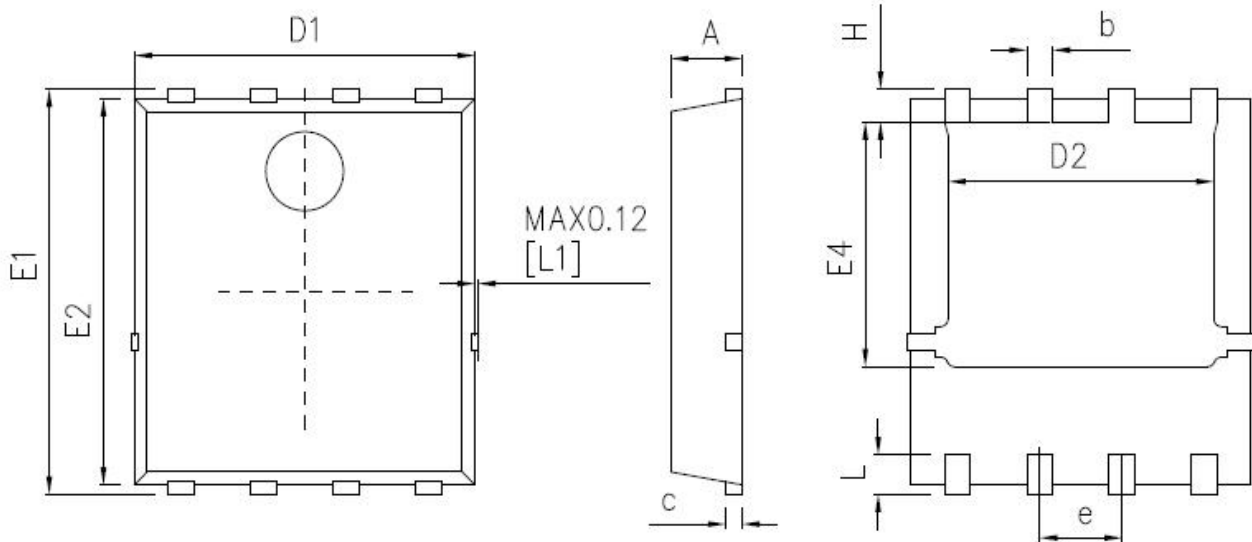


#### Diode Recovery Test Circuit & Waveform





**Mechanical Dimensions for DFN5×6**



DIMENSIONS IN MILLIMETERS		
SYMBOL	MIN	MAX
A	0.85	1.20
b	0.30	0.51
c	0.15	0.35
D1	4.80	5.40
D2	3.70	4.55
E1	5.95	6.35
E2	5.45	6.06
E4	3.30	3.92
e	1.27BSC	
L	0.3	0.71
H	0.38	0.71



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